

CLAIMS

Please cancel claims 12-17 and 23.

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A heat spreader, comprising:
 - a body formed from heat conductive material; and
 - a plurality of standoffs formed on a surface of said body to reduce bond thickness variation between said heat spreader and an integrated circuit to be coupled to said heat spreader, at least one of said plurality of standoffs ~~top to~~ have a flexible sealant material disposed between the at least one of said plurality of standoffs and a substrate coupled to the integrated circuit.
2. (Previously presented) The heat spreader of claim 1, wherein said body is plated with nickel.
3. (Previously presented) The heat spreader of claim 1, wherein said body is coated with heat-conductive organic material.

4. (Previously presented) The heat spreader of claim 1, wherein the surface further includes a plurality of mechanical attachment structures to couple to a package substrate with a sealant.

5. (Previously presented) A heat spreader, comprising:
a body formed from heat conductive material; and
a wall structure formed about a periphery of said body to couple to a package substrate through a flexible material.

6. (Previously presented) The heat spreader of claim 5, wherein said body is plated with nickel.

7. (Previously presented) The heat spreader of claim 5 wherein said body is coated with a heat-conductive organic material.

8. (Previously presented) An apparatus, comprising:
a heat spreader comprising heat conductive material and a wall structure;
and
a flexible material coupled to the wall structure and to couple to a package substrate.

9. (Previously presented) The apparatus of claim 8, wherein the flexible material comprises polymeric sealant material.

10. (Previously presented) The apparatus of claim 8, wherein said body is plated with nickel.

11. (Previously presented) The apparatus of claim 8, wherein said body is coated with a heat-conductive organic material.

12-17 (Cancelled)

18. (Previously presented) A semiconductor package, comprising:
a substrate having a top surface;
at least one semiconductor device attached to said top surface of said substrate; and
a cover secured to said substrate through a flexible sealant material and creating a space between said substrate and said cover, said semiconductor device residing within said space and secured to said substrate and said cover comprised of a heat-conductive material.

19. (Original) The semiconductor package of claim 18, wherein the cover is a heat spreader.

20. (Cancelled)

21. (Original) The semiconductor package of claim 19, wherein the cover has mechanical attachment structures bonded to the surface.

22. (Previously presented) The semiconductor package of claim 19, wherein the heat spreader has a wall structure about a periphery thereof to couple to said substrate.

23. (Cancelled)